

### Typical Applications

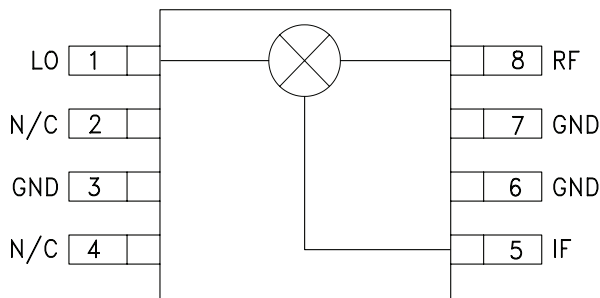
High Dynamic Range Infrastructure:

- GSM, GPRS & EDGE
- CDMA & W-CDMA
- Cable Modem Termination Systems

### Features

- +35 dBm Input IP3
- Conversion Loss: 8.8 dB
- No External Components
- Ultra Small MSOP Package: 14.8mm<sup>2</sup>
- Included in the HMC-DK003 Designer's Kit

### Functional Diagram



### General Description

The HMC400MS8 & HMC400MS8E are high dynamic range passive MMIC mixers in plastic surface mount 8 lead Mini Small Outline Packages (MSOP) covering 1.7 to 2.2 GHz. Excellent input IP3 performance of +36 dBm for down conversion and +29 dBm for up conversion is provided for 2.5G & 3G GSM/CDMA based UMTS or PCS applications at an LO drive of +17dBm. With a 1dB compression of +21 dBm, the RF port will accept a wide range of input signal levels. Conversion loss is 8.5dB typical and LO isolations are maintained at 22 to 33 dB. This miniature single-ended monolithic GaAs FET mixer does not require any external components or bias. The 50 to 300 MHz IF frequency response will satisfy many UMTS/PCS transmit or receive frequency plans configured for low side LO. The HMC400MS8 & HMC400MS8E input IP3 performance coupled with its high P1dB rivals traditional active FET mixers while offering a much smaller 14.8mm<sup>2</sup> standard IC footprint and no DC bias.

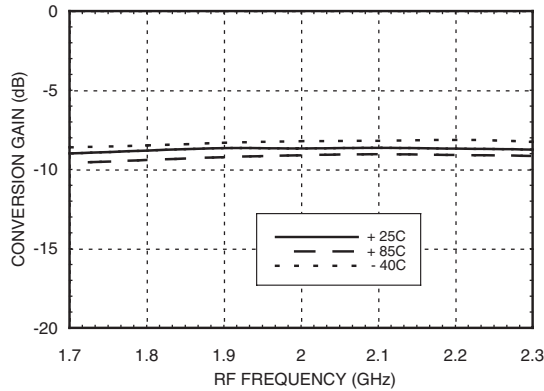
### Electrical Specifications, $T_A = +25^\circ\text{C}$ , LO = +17dBm, IF = 200 MHz\*

Parameter	Min.	Typ.	Max.	Min.	Typ.	Max.	Min.	Typ.	Max.	Units
Frequency Range, RF		1.7 - 1.8		1.8 - 2.0			2.0 - 2.2			GHz
Frequency Range, LO		1.4 - 1.75		1.5 - 1.95			1.7 - 2.15			GHz
Frequency Range, IF		DC - 300		DC - 300			DC - 300			MHz
Conversion Loss		9	11		8.8	10.5		8.8	10.5	dB
Noise Figure (SSB)		9	11		8.8	10.5		8.8	10.5	dB
LO to RF Isolation	29	33		24	30		20	25		dB
LO to IF Isolation	16	20		17	22		19	25		dB
IP3 (Input)	30	34		32	36		28	32		dBm
1 dB Gain Compression (Input)	18	21		18	21		18	22		dBm
LO Input Drive Level (Typical)		+16 to +18		+16 to +18			+16 to +18			dBm

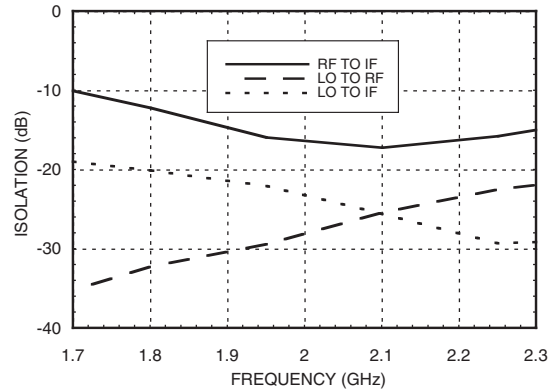
\*Unless otherwise noted, all measurements performed as a downconverter, with low side LO & IF = 200 MHz.



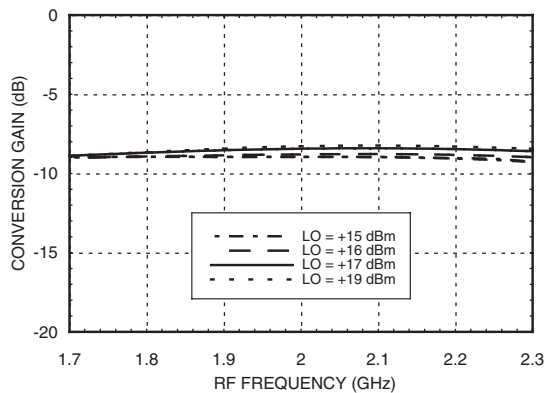
**Conversion Gain vs.  
Temperature @ LO = +17 dBm**



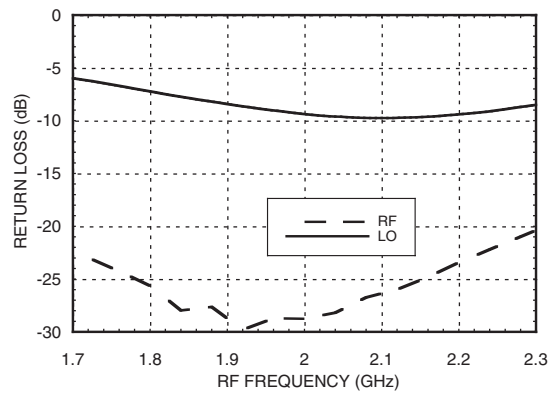
**Isolation @ LO = +17 dBm**



**Conversion Gain vs. LO Drive**

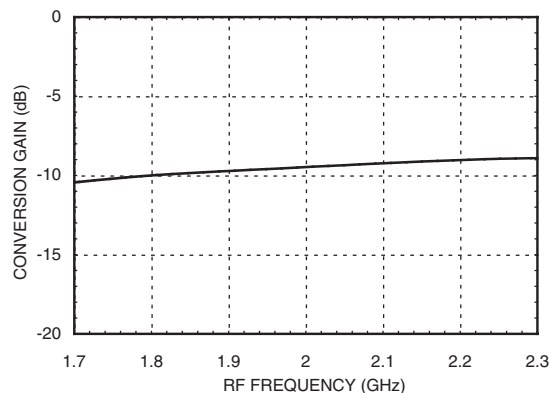


**Return Loss @ LO = +17 dBm**

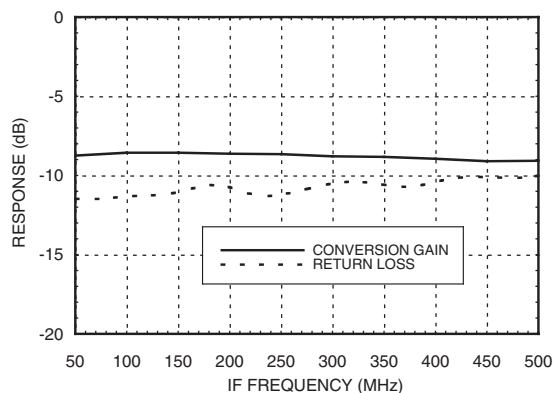


**Upconverter Performance**

**Conversion Gain @ LO = +17 dBm**

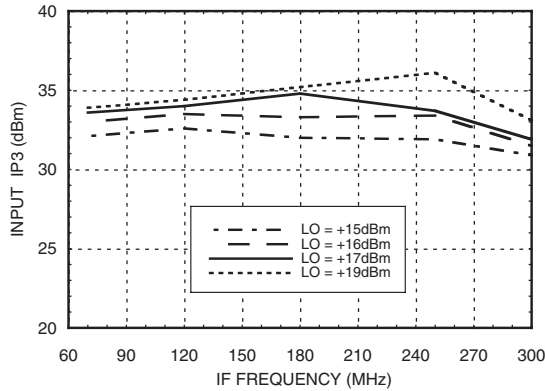


**If Bandwidth @ LO = +17 dBm**

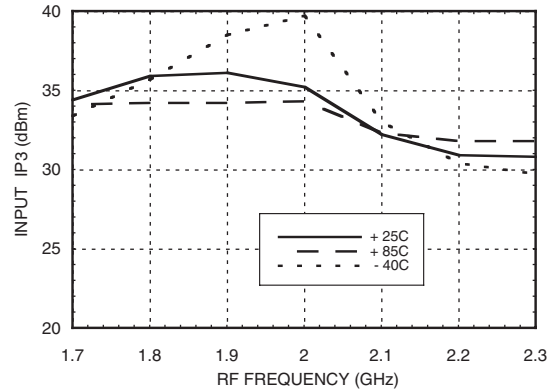


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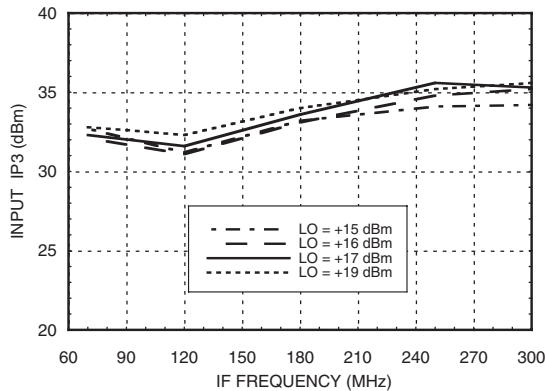
**Input IP3 vs. IF Frequency, RF = 1.75 GHz**



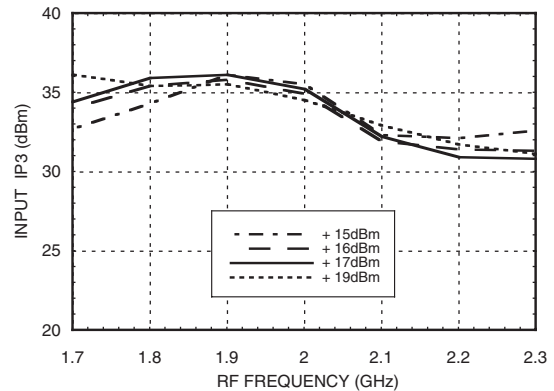
**Input IP3 vs. Temperature, LO = +17 dBm**



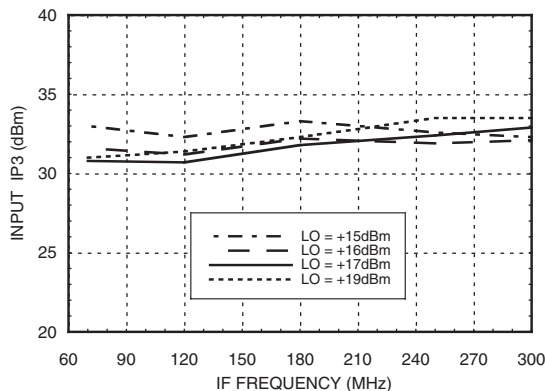
**Input IP3 vs. IF Frequency, RF = 1.95 GHz**



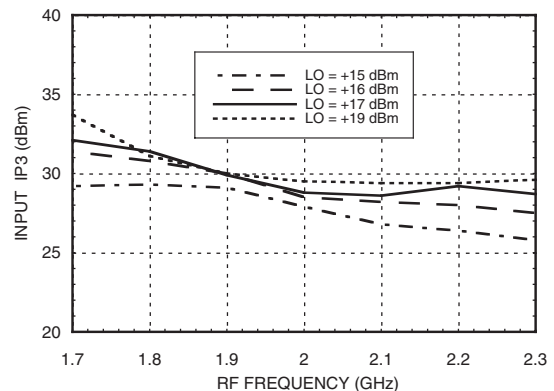
**Input IP3 vs. LO Drive**



**Input IP3 vs. IF Frequency, RF = 2.15 GHz**



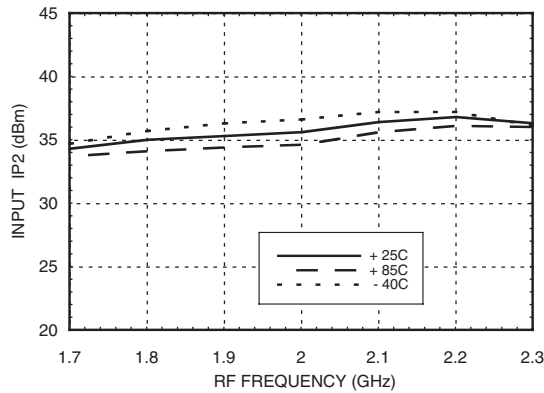
**Upconverter IP3 vs. LO Drive, IF = 200 MHz**



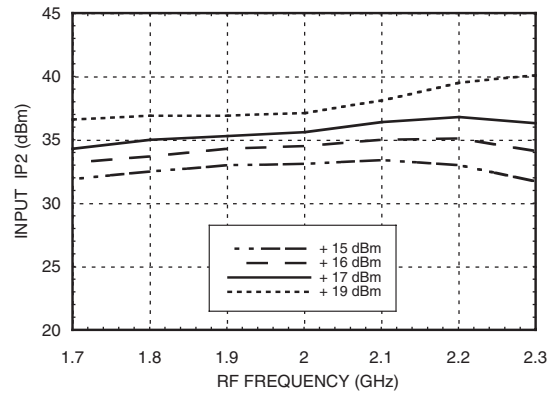
\*Unless otherwise noted, all measurements performed as a downconverter, with low side LO & IF = 200 MHz.



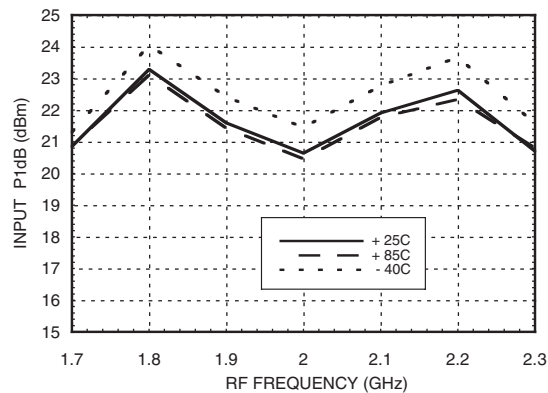
**Input IP2 vs. Temperature @ LO = +17 dBm**



**Input IP2 vs. LO Drive @ LO = +17 dBm**



**Input P1dB vs. Temperature @ LO = +17 dBm**



**MxN Spurious Outputs**

mRF	nLO				
	0	1	2	3	4
0	xx	-11	7	4	8
1	9	0	24	31	27
2	71	70	49	58	64
3	79	80	80	79	77
4	77	80	80	79	80

RF Freq = 2 GHz @ -10 dBm  
 LO Freq = 1.8 GHz @ +17 dBm  
 All values in dBc relative to the IF output power.

**Harmonics of LO**

LO Freq (GHz)	nLO Spur @ RF Port			
	1	2	3	4
1.4	42	26	56	46
1.55	33	25	56	53
1.7	29	29	49	50
1.85	26	31	44	53
2	24	36	44	48
2.15	21	38	43	49

LO = +17 dBm  
 All values are in dBc below input LO level @ RF port.

**Absolute Maximum Ratings**

RF/IF Input	+27 dBm
LO Drive	+27 dBm
Storage Temperature	-65 to +150 °C
Operating Temperature	-40 to +85 °C
IF DC Current	±40 mA

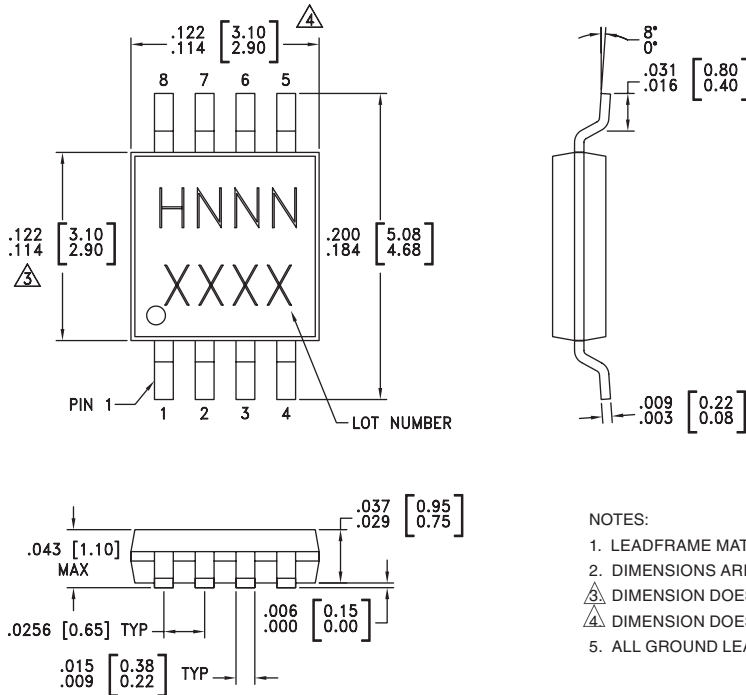


**ELECTROSTATIC SENSITIVE DEVICE  
 OBSERVE HANDLING PRECAUTIONS**

\*Unless otherwise noted, all measurements performed as a downconverter, with low side LO & IF = 200 MHz.



**Outline Drawing**



- NOTES:
1. LEADFRAME MATERIAL: COPPER ALLOY
  2. DIMENSIONS ARE IN INCHES [MILLIMETERS]
  - △ DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.15mm PER SIDE.
  - ▲ DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.25mm PER SIDE.
  5. ALL GROUND LEADS MUST BE SOLDERED TO PCB RF GROUND.

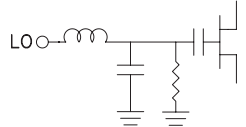

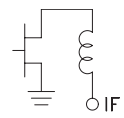
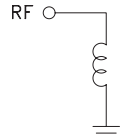
**Package Information**

Part Number	Package Body Material	Lead Finish	MSL Rating	Package Marking <sup>[3]</sup>
HMC400MS8	Low Stress Injection Molded Plastic	Sn/Pb Solder	MSL1 <sup>[1]</sup>	H400 XXXX
HMC400MS8E	RoHS-compliant Low Stress Injection Molded Plastic	100% matte Sn	MSL1 <sup>[2]</sup>	H400 XXXX

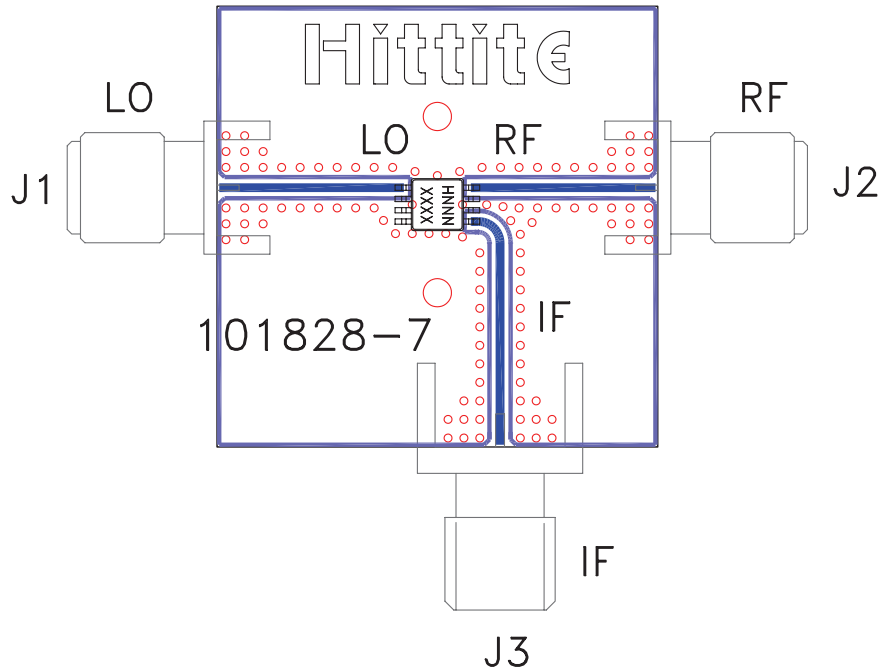
[1] Max peak reflow temperature of 235 °C  
 [2] Max peak reflow temperature of 260 °C  
 [3] 4-Digit lot number XXXX



### Pin Descriptions

Pin Number	Function	Description	Interface Schematic
1	LO	This pin is AC coupled & matched to 50 Ohms from 1.4 to 2.2 GHz. Blocking capacitors are required if line potential is not equal to 0V.	
2, 4	N/C	Not connected.	
3, 6, 7	GND	This pin must be connected to RF ground.	
5	IF Port	This pin is DC coupled. For applications not requiring operation to DC this port should be DC blocked externally using a series capacitor. Choose value of capacitor to pass IF frequency desired. For operation to DC, this pin must not sink/source more than 40 mA of current or failure may result.	
8	RF Port	This pin is DC coupled & matched to 50 Ohm from 1.7 to 2.2 GHz	

### Evaluation PCB



### List of Materials for Evaluation PCB 101830 [1]

Item	Description
J1 - J3	PCB Mount SMA RF Connector
U1	HMC400MS8 / HMC400MS8E Mixer
PCB [2]	101828 Eval Board

[1] Reference this number when ordering complete evaluation PCB

[2] Circuit Board Material: Rogers 4350

The circuit board used in the final application should use RF circuit design techniques. Signal lines should have 50 ohm impedance while the package ground leads and exposed paddle should be connected directly to the ground plane similar to that shown. A sufficient number of VIA holes should be used to connect the top and bottom ground planes. The evaluation circuit board shown is available from Hittite upon request.



MICROWAVE CORPORATION v02.0705



## HMC400MS8 / 400MS8E

*HIGH IP3 GaAs MMIC  
MIXER, 1.7 - 2.2 GHz*

**Notes:**

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MIXERS - SMT